



1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE
4. LEAD COPALANARITY IS 0.003 INCH MAX.

SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN.	NDM	MIN.	NDM
A	1.524	1.626	0.060	0.064
A1	0.102	0.152	0.004	0.006
A2		1.499		0.059
b	0.203		0.305	0.008
c	0.178		0.254	0.007
D	4.775	4.902	0.188	0.193
E	5.84	5.994	0.228	0.236
E1	3.810	3.912	0.150	0.154
L	0.406	0.635	0.016	0.025
L1	0.254 BASIC		.010 BASIC	
h	0.254	0.330	0.010	0.013
e	0.635 BASIC		.025 BASIC	
phi	0		8	0
N	16			
REF	JEDEC MD-137 VARIATION AB			



TITLE:  
PDD for 16 SSDP(150MIL),  
0.635MM PITCH

DATE:

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REV. A

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# Document History Page

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Rev.	ECR No.	Date	Orig. of Change	Description of Change
A	ECR-694	7/7/2008	RP	NEW RELEASE